		DB	Time stamp	
L Number	Hits Search Text	USPAT; US-PGPUB;	2002/07/29 10:55	
i i	215 smart with label	EPC; JPO; DERWENT; IBM TDB		
2	10837 smart with card	USPAT; US-PGPUB; EPO; JPC; DERWENT;	. 2002/07/29 ; 10:55	
. 3	80712 (flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IEM TDB	2002/07/29 10:57	
4	19830 hard with particles	USPĀT; US-PGPUB; EPO; JPO;	2002/07/29 10:57	
5	719715 flip bumps balls flipchip	DERWENT; IEM_TDB USPAT; US-FGPUB; EPO; JFO; DERWENT;	2002/07/29	i i i
6	556 (hard with particles) same (flip bumps balls flipchip)	IEM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;		
7	2 ((hard with particles) same (flip bumps balls flipchip)) and (smart with label)	IBM_TDB USPAT; US-PGPUB EPO; JPO DERWENT;	;	
: : : 8	10 (smart with card) and (hard with particles)	IBM_TDB USPAT; US-PGPUE EPO; JPC DERWENT;	2002/07/29 3; 11:05	
9	733 (smart with card) and (flip bumps balls flipchip)	IBM_TDB USPAT; US-PGPUI EPO; JPO DERWENT	2002/07/29 B; 11:14 O;	
10	567 ((smart with card) and (flip bumps ball flipchip)) and (chip flip)	DERWENT	B; 11:15 0; 11:15	
11	83 (((smart with card) and (flip bumps bal flipchip)) and (chip flip)) and particl	DERWENT	72002/07/29 JB; 11:06 PO; 1	
12	(smart with label) and (flip bumps ball flipchip)	EPO; C DERWEN	2002/07/29 UB; 11:14 PO; T;	
13	22 ((smart with label) and (flip bumps ba flipchip)) and (chip flip)	IBM_TD USPAT; US-PGP EPO; J DERWEN IBM TI	2002/07/23 puB; 11:23 ppO;	,

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. 14	11882	((flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/29 11:23
15	4838	(((flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip)) and (flip bumps balls	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/29 11:23
16	4838	flipchip) ((((flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip)) and (flip bumps pb wb)) and ((flexible moveable)) and ((flexible moveable))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TEB	2002/07/29
17	55	bendable adjustable) with (chip flip)) board pcb cb pb wb)) and (chip flip)) ((((flexible moveable bendable adjustable) with (substrate board pcb cb pb wb)) and (chip flip)) and (flip bumps balls flipchip)) and (hard with	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/29 11:24
1.1 - 1		particles)	, 571 -	